

To: PSMA Capacitor Committee
From: Fred Weber - Committee Co-Chair
Date: August 20, 2014
RE: Minutes for committee meeting August 20, 2014

Today's meeting fine tuned the theme for our Industrial Session and discussed the possibility of adding a 7th presentation for APEC 2015 in Charlotte.

The theme for the Industry Session has been changed from: "Capacitor Applications Dictate Capacitor Design" to "**Applications Dictate Capacitor Technology**". This would be followed up by a descriptive paragraph:

GaN and SiC continue to advance traditional design parameters pushing Capacitor capability to meet higher frequencies and higher temperatures. Embedded and 3D solutions also are growing and are reshaping capacitor needs.

There is still time to make changes so feel free to make suggestions.

We have a preliminary slate of six authors/organizations as listed.

- 1) Joe Bond of Electronic Concepts will discuss one or more high temperature film capacitor applications.
- 2) James Lewis of Kemet will discuss capacitors for automobile applications and infotainment.
- 3) We have a request by Nihal Kalaratna to provide a presentation on Supercapacitors. If this is a viable presentation it may be included. James Lewis said Kemet can provide a presenter on supercapacitors if needed as an option.
- 4) Scott Franco of Cornell Dubilier said his company may be interested in providing a presentation on aluminum electrolytic technology. **Ralph Kerrigan took an action to follow up with him – we did not have an update for today's meeting.**
- 5) Eric Persson of International Rectifier said he can provide a presentation on the Unique criteria of capacitors for ultra high frequency applications. Fred Weber contacted him and he confirmed he is interested in doing this.
- 6) Ralph Kerrigan of NWL will provide a presentation of film capacitor technology For DC link applications.

We have a possible 7th presentation. Luis Burgyan will follow up with Murata, and internally to Ltec with Arnold to see if anyone would be interested in presenting on the subject of **Capacitor packaging needs in the 3D and Embedded arena.**

The next meeting will be Thursday, September 11th at 11 am CST.